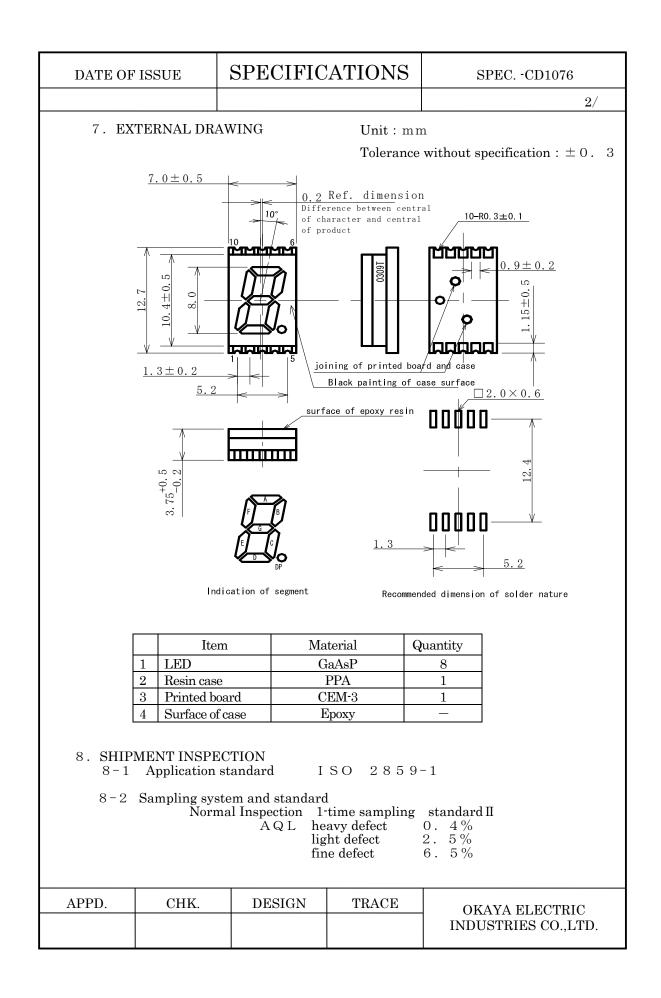


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Forward direct currentII2 0mAReverse voltage V_R 5 V Storage temperatureT s t g $-40 \sim +80$ \mathbb{C} Operating temperatureT o p r $-30 \sim +70$ \mathbb{C} Solder temperatureT s o 1 350 \mathbb{C} Solder temperatureT s o 1 100 2.40 Forward voltage V_F $I_F=10mA$ SEG 1.90 2.40 Reverse current I_R $V_R=4V$ 100 μA Luminous intensity I_V $I_F=10mA$ SEG 0.7 2.0 Peak emission λP $I_F=10mA$ 632 nm	
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$ \begin{array}{ c c c c c c c c } \hline Storage temperature & T s t g & -40 \sim +80 & \ensuremath{\mathbb{C}} \\ \hline Operating temperature & T o p r & -30 \sim +70 & \ensuremath{\mathbb{C}} \\ \hline Solder temperature & T s o l & & & & & & & & & & & & & & & & & &$	
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Solder temperatureT s o 13 5 0 within 3 sec.5. ELECTRO-OPTICAL CHARACTERISTICST a = 2 5 °C (per segment RCN-SDA03R3NLItemSymbolConditionMINTYPMAXUnit MAXForward voltage V_F $I_F=10mA$ SEG1.902.40 VVReverse current I_R $V_R=4V$ 100 μA DP1.902.40 MAXVLuminous intensity I_V $I_F=10mA$ SEG0.72.0mcdPeak emission λP $I_r=10mA$ 632nm	
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5. ELECTRO-OPTICAL CHARACTERISTICS T a = 2 5 °C (per segment RCN-SDA03R3NL Item Symbol Condition MIN TYP MAX Unit Forward voltage V_F $I_F=10mA$ SEG 1.90 2.40 V Reverse current I_R $V_R=4V$ 100 μA Luminous intensity I_V $I_F=10mA$ SEG 0.7 2.0 mod Peak emission λP $I_F=10mA$ 632 mm	
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$ \begin{array}{ c c c c c c c c } \hline Item & Symbol & Condition & MIN & TYP & MAX & Unit \\ \hline Forward voltage & V_F & I_F=10mA & SEG & 1.90 & 2.40 & V \\ \hline Forward voltage & V_F & I_F=10mA & DP & 1.90 & 2.40 & V \\ \hline Reverse current & I_R & V_R=4V & 100 & \muA \\ \hline Luminous intensity & I_V & I_F=10mA & SEG & 0.7 & 2.0 & mcd \\ \hline Peak emission & \lambdaP & & & & & & & & & & & & & & & & & $,
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Forward voltage V_F $I_F=10mA$ DP 1.902.40 V Reverse current I_R $V_R=4V$ 100 μA Luminous intensity I_V $I_F=10mA$ SEG 0.72.0mcdPeak emission λP $I_F=10mA$ 632 nm	<u></u>
Luminous intensity I_v $I_F=10mA$ SEG0.72.0mcdPeak emission λP $I_F=10mA$ 632nm	
Luminous intensity $I_F=10mA$ DP0.180.5mcdPeak emission λP $I_F=10mA$ 632nm	
DP0.180.5Peak emission λP Ir=10mA632nm	
$I_{\rm F}=10{\rm mA}$ 632 nm	
wovelength IF-10mA 632 nm	
wavelength	
Spectra half-width $\Delta\lambda$ I _F =10mA 35 nm	
6. CIRCUIT DIAGRAM / TERMINAL CONNECTION	
CA 3 8 1 Cathode E	
2 C athode D	
3 A node C 0 M 4 C athode C	
5 Cathode D.P	N
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	2°
8 Anode COM)
7 6 4 2 1 9 10 5 9 Cathode F	
10 Cathode G	
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n	

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DATE (OF ISSUE	SPECIFICA	ATIONS	SPECCD1076					
					3/				
8 -	8-3 Inspection item, judgment standard, and defect classification								
No.	Inspection item	Judgement system Classif -cation							
1 2	open short	consider as defect consider as defect	consider as defect for those not turned on. consider as defect for those not turned on. consider as defect for those carries out simultaneous lighting						
3	Luminescence color	consider as det	consider as defect for those not a regular luminescence color He						
4	Different model mixing		consider as defect for those other models are mixing defect						
5	Marking	without marking		ith wrong marking or					
6	Insufficient quantity	product quantity.		with insufficient of					
7	Characteris-t ics	specification of consider as defec satisfied of the	consider as defect for those not satisfied with the specification of electrical property. consider as defect for those luminous intensity not satisfied of the minimum value of specification.						
8	Appearance	to the specificat	onsider as defect for those appearance not satisfied o the specification size. onsider as defect for those color tone different						
9	Color tone	consider as defect for those color tone different between segments. consider as defect when garbage or decimal point as							
10	Garbage Air bubbles	 mentioned below mixing in a segment Black garbage exceeding diameter of 0.3mm White garbage exceeding diameter of 0.4mm Thread garbage exceeding of 3.0mm air bubbles in the luminescence surface of product. consider as defect when exceeding 2 places of dia.0.3mm consider as fine product when air bubbles are on the 							
12	Printing	the side of the product. a crack in the printing part of the reflective board surface consider as defect when exceeding 2 places of 0.2mm × 3.0mm. separation in the printing part of the reflective board surface consider as defect when exceeding 2 places of dia.3mm							
13	Surface crack	a crack in a luminescence side of product consider as defect when places on a plate and the float of a product exceeds 0.3mm							
14	Resin adhesion	in which resin adhered to the back of the product consider as defect when places on a plate and the float of a product exceeds 0.3mm							
15	Segment shape Resin	thick or narrow changes in a part of segment consider as defect when exceeding 0.2mm consider as defect when the barricade exceeding							
16	barricade	tolerance size of							
APPD.	. CHK. DESIGN TRACE OKAYA ELECTRIC INDUSTRIES CO.,LT								

DATE OF	ISSUE	SPECIFICATIONS SPECCD1076								
				4/						
9. PACKING FORM										
(1) Taping specifications Lead Tape :										
	Pull out direction									
		Empty	Mounting	mpty art						
		Min.20cm		Min.20cm						
Τa	ape exfoliation i		~0.8N							
	☐ Tape sending speed : 5mm/s									
				-						
	Carry tape									
Tape sending direction										
Tape bending intensity : If a tape is bent in the radius of 50mm or less,										
	a cover tape may separate. Connection of a tape : There should be no connection of the cover tape and									
		carry tape	within 1 reel							
Pa	Packing quantity : Standard quantity considers as 1,400 piece / reel.									
Others : The omission of the product in the product enclosure part of a mounting										
	part is taken as less than three continuation. The product contained should move easily in each receipt hole									
Adhesion on the cover tape of a product is not allowed.										
	1									
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				INDUSTRIES CO.,LTD.						

DATE OF ISSUE	SPECIFICATIONS	SPECCD1076							
		5/							
(2) Indication	n of label								
TYPE	TYPE \leftarrow Indication of product name (model)								
LOT NO.	LOT NO. \leftarrow Indication of lot								
QUANTITY	QUANTITY ← Indication of quantity								
DATE									
NOTE									
	ELECTRIC INDUSTRIES CO.	, LTD							
Indication of le	ot :								
example)	0 3 0 9 T T : symbol of manu month: 01~12 year: 03 for year								
(3) Prevention-of	-moisture								
Packing by th	Packing by the aluminum pack is performed in order to avoid the moisture								
absorption ur	nder shipping and storage of the p	roduct.							
alumi pack									
Storage conditions.									
-	age with the following conditions	after open.							
_	by which humidity-temperature	-							
- keep it in a dry box		0							
	 seal and keep with commercial silica, drier etc. 								
-									
direct rays hit.		r							
-	erature change may generates dev	v condensation, oxidization							
	please keep it in a place with low								
	load at the time of storage.								
	he place with poisonous gas (espe	cially corrosive gas), nor a							
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				INDUSTRIES CO.,LTD.

DA	DATE OF ISSUE SPEC		CIFICATIONS		3	SPECCD1076	
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	(4) Shape	and reference					
	Item		Sym -bol	Reference dimension (mm)		Remarks	
	Dent hole for	Vertical	А	7.6		ne internal size excluding the rner R section	
	product	Horizontal	В	13.1	Th co:	ne internal size excluding the rner R section	
	insertion	Pitch	P 1	12.0			
		Major axis	D0	1.5			
	Round sending hole	pitch	P 0	4.0		cumulation tolerance 0.5mm/ 10 pitch	
	senaing note	position	Е	1.75		stance between tape end and nding hole	
	Distance	Vertical direction	P 2	2.0		stance between dent hole and ntral line of round sending hole.	
	between central lines	Horizontal direction	F	11.5		stance between dent hole and ntral line of round sending hole.	
	Course to a s	Width	W 1	21.5			
	Cover tape	Thickness	tз	0.1			
	Carry tape	Width	W 0	24.0			
	Juri Jupe	Thickness	t 1	0.4	<u> </u>		
	Overall thickness		t 2	4.2	Sy	nthesis of cover tape and carry tape	
	※ Material : F	oiystyrene					
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DATE	YE OF ISSUE SPECIFICATIONS					IS	SPECCD1076		
	(5) Shape and reference dimension of reel 7/								
	L;	abel							
		Item			Symbol	Reference dimension (mm)			
		diameter			А	φ 330			
]	Flange	Thickness	less		t	2.0			
		Inner int flanges				25.5	The size is to be the axial central part		
		Perimeter	Perimeter diameter			φ 100			
]	Hub	Diameter of	ter of spindle hole		С	ϕ 13			
		Kev slot		Width	E U	2.0			
	Indication of product name					4.0 ich indicated ide of a flange	items, quantity, and the lot e is to be attached		
	※ Mate	rial : Polyst	yrene						
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